

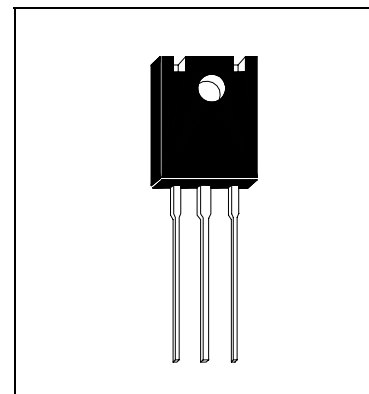


HSC2682

NPN EPITAXIAL PLANAR TRANSISTOR

Description

Audio frequency power amplifier, high frequency power amplifier.



Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
Storage Temperature -50 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 1.2 W
Total Power Dissipation (Tc=25°C) 8 W
- Maximum Voltages and Currents
BVCBO Collector to Base Voltage 180 V
BVCEO Collector to Emitter Voltage 180 V
BVEBO Emitter to Base Voltage 5 V
IC Collector Current 100 mA

Electrical Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	180	-	-	V	IC=1mA
BVCEO	180	-	-	V	IC=10mA
BVEBO	5	-	-	V	IE=10uA
ICBO	-	-	1	uA	VCB=180V
IEBO	-	-	1	uA	VEB=3V
*VCE(sat)	-	120	500	mV	IC=50mA, IB=5mA
*VBE(sat)	-	0.8	1.5	V	IC=50mA, IB=5mA
*hFE1	90	-	-		IC=1mA, VCE=5V
*hFE2	100	200	320		IC=10mA, VCE=5V
fT	-	200	-	MHz	IC=20mA, VCE=10V
Cob	-	-	5	pF	VCB=10V

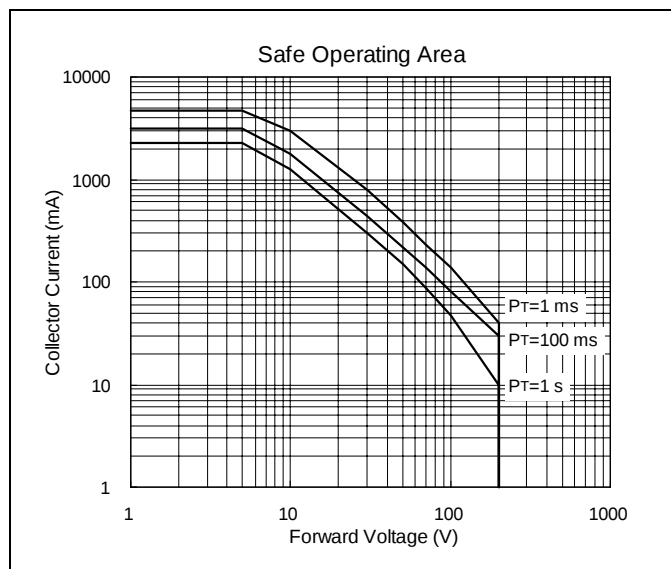
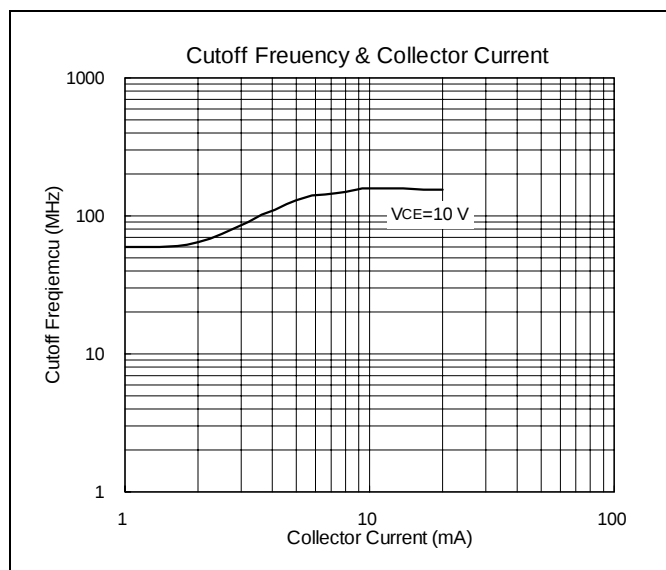
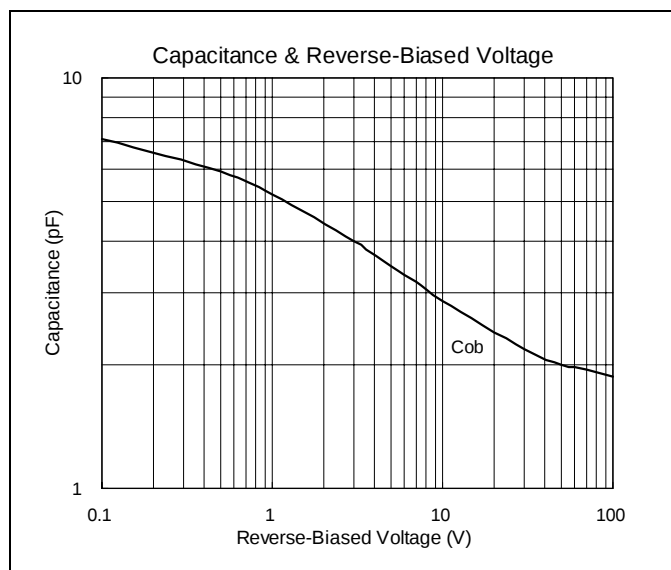
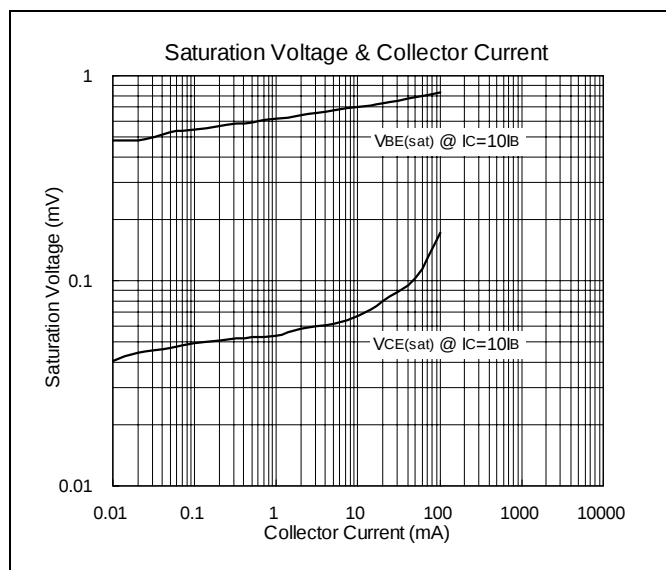
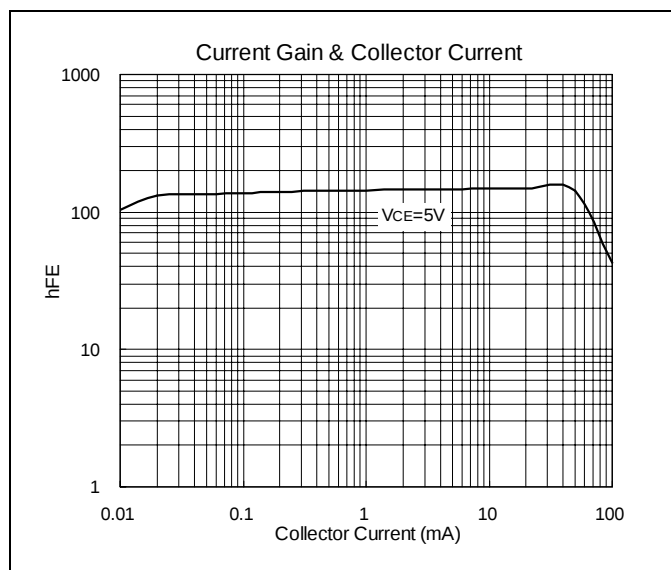
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

Classification Of hFE2

Rank	O	Y
Range	100-200	160-320

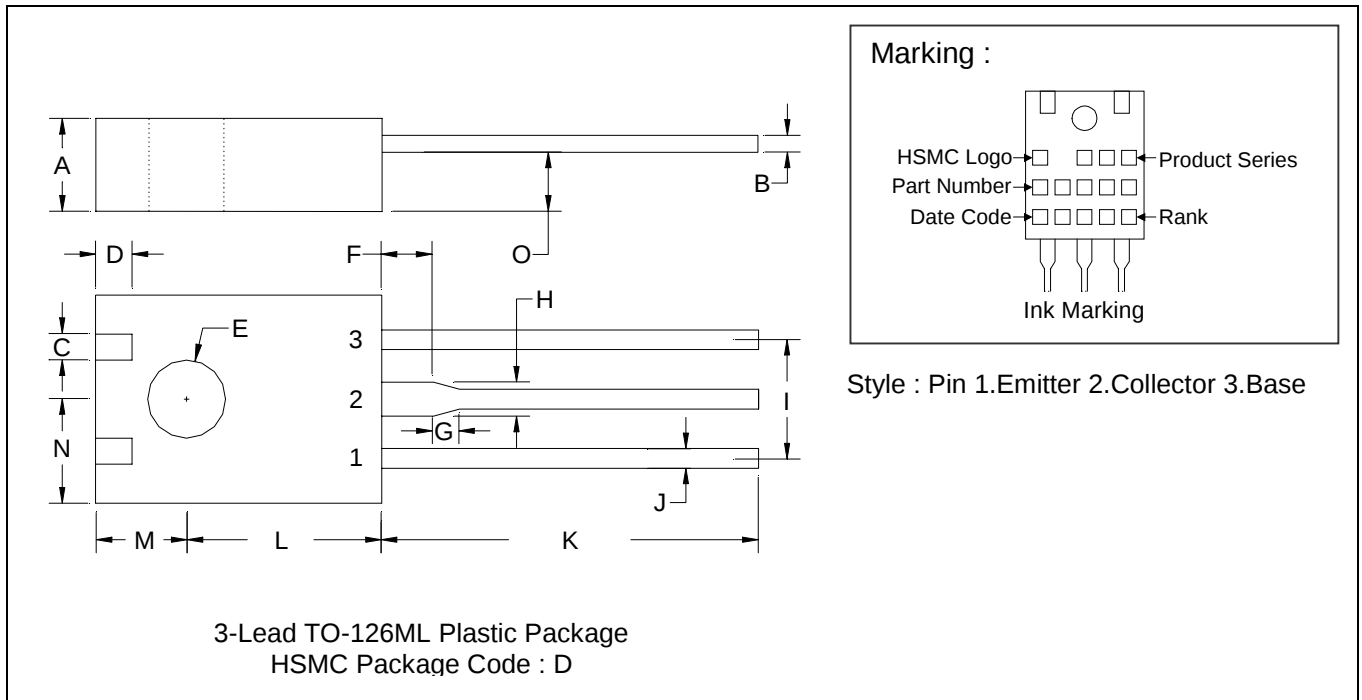


Characteristics Curve





TO-126ML Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1356	0.1457	3.44	3.70	I	-	*0.1795	-	*4.56
B	0.0170	0.0272	0.43	0.69	J	0.0268	0.0331	0.68	0.84
C	0.0344	0.0444	0.87	1.12	K	0.5512	0.5906	14.00	15.00
D	0.0501	0.0601	1.27	1.52	L	0.2903	0.3003	7.37	7.62
E	0.1131	0.1231	2.87	3.12	M	0.1378	0.1478	3.50	3.75
F	0.0737	0.0837	1.87	2.12	N	0.1525	0.1625	3.87	4.12
G	0.0294	0.0494	0.74	1.25	O	0.0740	0.0842	1.88	2.14
H	0.0462	0.0562	1.17	1.42					

Notes : 1.Dimension and tolerance based on our Spec. dated Mar. 6,1995.

2.Controlling dimension : millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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